

Z-PACK 2mm Futurebus + Power Modules, Vertical Pin Assemblies

Pin Assemblies with Solder Leads and Compliant Press-Fit Leads

Material and Finish:

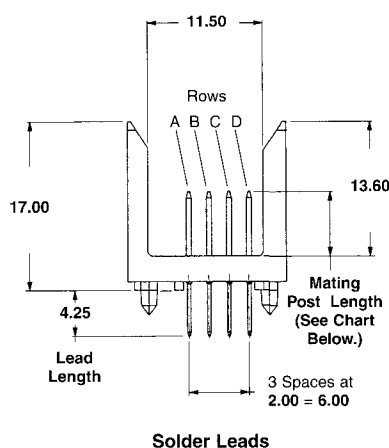
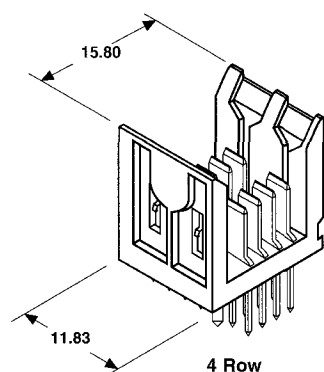
Housing — Liquid crystal polymer
Pin Contacts — Phosphor bronze, mating surface plating conforms to all testing specified for Telcordia Uncontrolled Environment, with entire contact underplated with 0.00127 min. nickel. See customer drawing for specific lead plating.

Related Product Data:

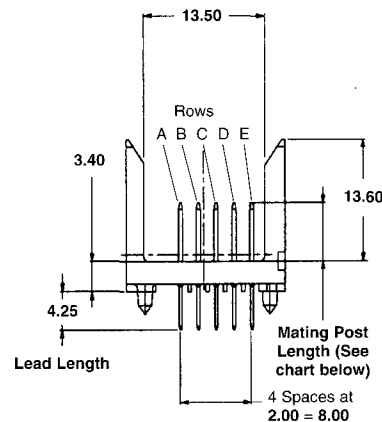
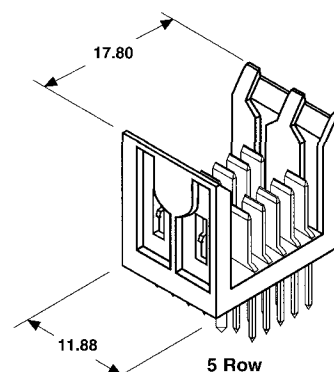
Current Rating — 5 Amperes per contact
Mating Force — 2.4N per contact max.
Unmating Force — 0.3N per contact max.
Durability — 250 cycles

Technical Documents:

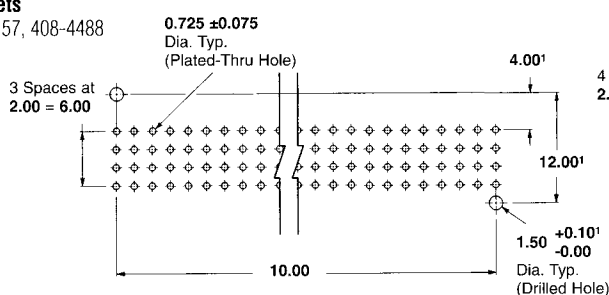
Product Specification
 108-1441
Application Specification
 114-1075
Instruction Sheets
 408-6927, 408-4157, 408-4488



Solder Leads

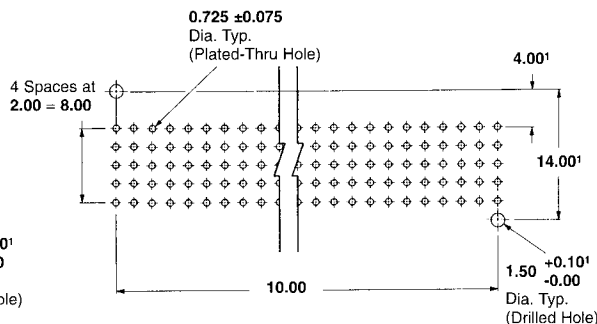


Solder Leads



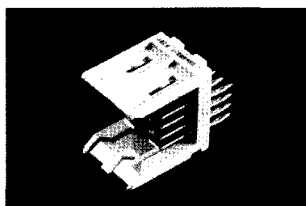
Recommended PC Board Hole Layout per IPC-D-300, Type II, Class C (Component Side)

¹Dimensions apply to solder lead versions only.



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Number of Positions	Mating Post Length	Part Numbers		
		Solder Tails	Press-Fit	Seating Tool
8	0.256 [6.5]	536600-1	536603-1	58512-1
	0.315 [8]	—	536620-1	—
10	0.256 [6.5]	—	536642-1	1214224-1
	0.315 [8]	—	536642-7	—

Notes: Contact Tyco Electronics for additional sizes
 For contact load variations (sequenced or select-load pins), use worksheet on page 49 to define specific requirements.